

## 1. General description

Planar passivated Silicon Controlled Rectifier in a TO-247 plastic package intended for use in applications requiring very high inrush current capability and high thermal cycling performance. This product is qualified to AEC-Q101 standard for use in automotive applications.



AEC - Q101 Qualified



**Lead-Free**

## 2. Features and benefits

- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- High voltage capacity
- Very high current surge capability
- AEC-Q101 compliant

## 3. Applications

- Automotive battery charging (on-board and off-board)
- Solid State Relay (SSR)
- Uninterruptible Power Supply (UPS)
- Inrush protection and soft-start
- AC and DC motor controls
- Heating controls
- AC Power rectification
- Renewable energy inverters
- Industrial welding systems

## 4. Quick reference data

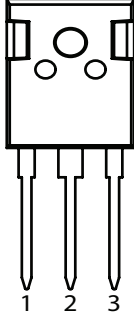

Table 1. Quick reference data

| Symbol                         | Parameter                            | Conditions  | Min | Typ | Max  | Unit |
|--------------------------------|--------------------------------------|---|-----|-----|------|------|
| <b>Absolute maximum rating</b> |                                      |   |     |     |      |      |
| $V_{DRM}$                      | repetitive peak off-state voltage    |   | -   | -   | 1200 | V    |
| $V_{RRM}$                      | repetitive peak reverse voltage      |   | -   | -   | 1200 | V    |
| $I_{TSM}$                      | non-repetitive peak on-state current | half sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | -   | -   | 650  | A    |
|                                |                                      | half sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$  | -   | -   | 715  | A    |
| $T_j$                          | junction temperature                 |   | -   | -   | 150  | °C   |
| $I_{T(AV)}$                    | average on-state current             | half sine wave; $T_{mb} \leq 131\text{ °C}$   | -   | -   | 50   | A    |

| Symbol                         | Parameter                         | Conditions   | Min  | Typ | Max | Unit             |
|--------------------------------|-----------------------------------|--|------|-----|-----|------------------|
| $I_{T(RMS)}$                   | RMS on-state current              | half sine wave; $T_{mb} \leq 131\text{ }^{\circ}\text{C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>                  | -    | -   | 79  | A                |
| <b>Static characteristics</b>  |                                   |  |      |     |     |                  |
| $I_{GT}$                       | gate trigger current              | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ;<br><a href="#">Fig. 7</a> ; <a href="#">Fig. 8</a>                     | -    | -   | 50  | mA               |
| <b>Dynamic characteristics</b> |                                   |  |      |     |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage | $V_{DM} = 804\text{ V}$ ; $T_j = 125\text{ }^{\circ}\text{C}$ ; $R_{GK} = 100\text{ }\Omega$ ;<br>( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform | 1500 | -   | -   | V/ $\mu\text{s}$ |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                       | Simplified outline  | Graphic symbol   |
|-----|--------|-----------------------------------|---|--|
| 1   | K      | cathode                           |  | <br>sym037 |
| 2   | A      | anode                             |   |  |
| 3   | G      | gate                              |   |  |
| mb  | A      | mounting base; connected to anode |   |  |

## 6. Ordering information

Table 3. Ordering information

| Type number    | Package name | Orderable part number | Packing method | Small packing quantity | Package version | Package issue date |
|----------------|--------------|-----------------------|----------------|------------------------|-----------------|--------------------|
| BT155W-1200T-A | TO-247       | BT155W-1200T-AQ       | Tube           | 30                     | TO-247N         | 20-Jul-2016        |

## 7. Marking

Table 4. Marking codes

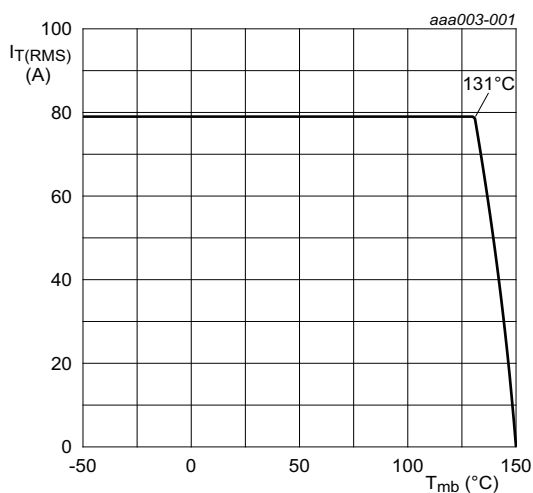
| Type number    | Marking codes  |
|----------------|----------------|
| BT155W-1200T-A | BT155W-1200T-A |

## 8. Limiting values

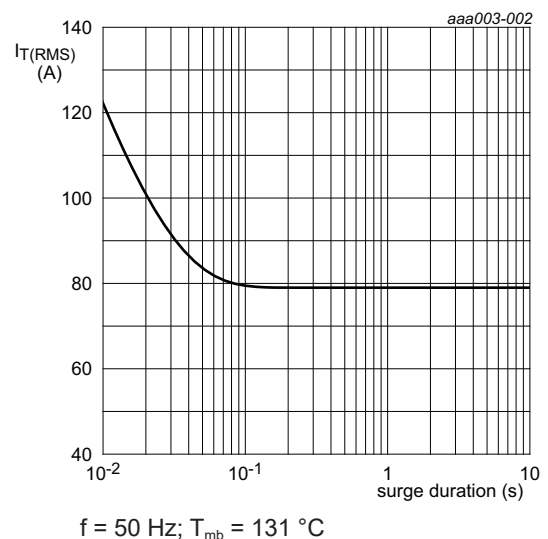
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol       | Parameter                            | Conditions   | Min | Max  | Unit             |
|--------------|--------------------------------------|--|-----|------|------------------|
| $V_{DRM}$    | repetitive peak off-state voltage    |  | -   | 1200 | V                |
| $V_{RRM}$    | repetitive peak reverse voltage      |  | -   | 1200 | V                |
| $I_{T(AV)}$  | average on-state current             | half sine wave; $T_{mb} \leq 131\text{ °C}$  | -   | 50   | A                |
| $I_{T(RMS)}$ | RMS on-state current                 | half sine wave; $T_{mb} \leq 131\text{ °C}$ ;<br><a href="#">Fig 1</a> ; <a href="#">Fig 2</a> ; <a href="#">Fig 3</a> | -   | 79   | A                |
| $I_{TSM}$    | non-repetitive peak on-state current | half sine wave; $T_{J(init)} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$ ;<br><a href="#">Fig 4</a> ; <a href="#">Fig 5</a> | -   | 650  | A                |
|              |                                      | half sine wave; $T_{J(init)} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$   | -   | 715  | A                |
| $I^2t$       | $I^2t$ for fusing                    | $t_p = 10\text{ ms}$ ; sine-wave pulse   | -   | 2113 | A <sup>2</sup> s |
| $di_T/dt$    | rate of rise of on-state current     | $I_G = 100\text{mA}$   | -   | 150  | A/ $\mu\text{s}$ |
| $I_{GM}$     | peak gate current                    |  | -   | 8    | A                |
| $V_{RGM}$    | peak reverse gate voltage            |  | -   | 5    | V                |
| $P_{GM}$     | peak gate power                      |  | -   | 20   | W                |
| $P_{G(AV)}$  | average gate power                   | over any 20 ms period  | -   | 1    | W                |
| $T_{stg}$    | storage temperature                  |  | -40 | 150  | °C               |
| $T_j$        | junction temperature                 |  | -   | 150  | °C               |



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



**Fig. 2. RMS on-state current as a function of surge duration; maximum values**  
 $f = 50\text{ Hz}$ ;  $T_{mb} = 131\text{ °C}$

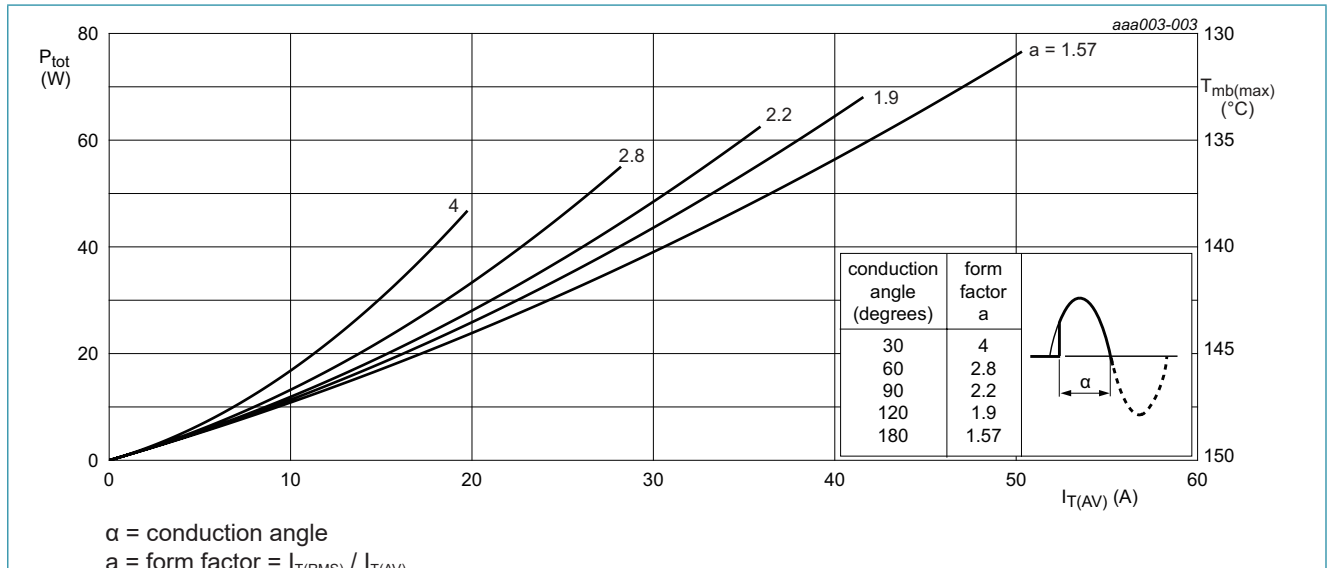


Fig. 3. Total power dissipation as a function of average on-state current; maximum values

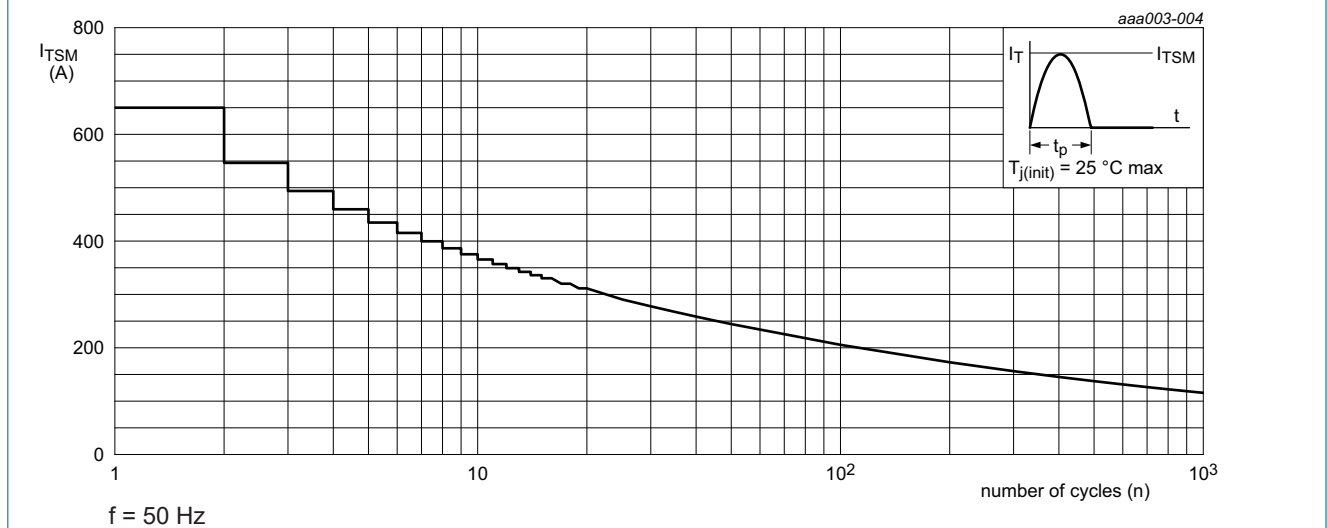


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

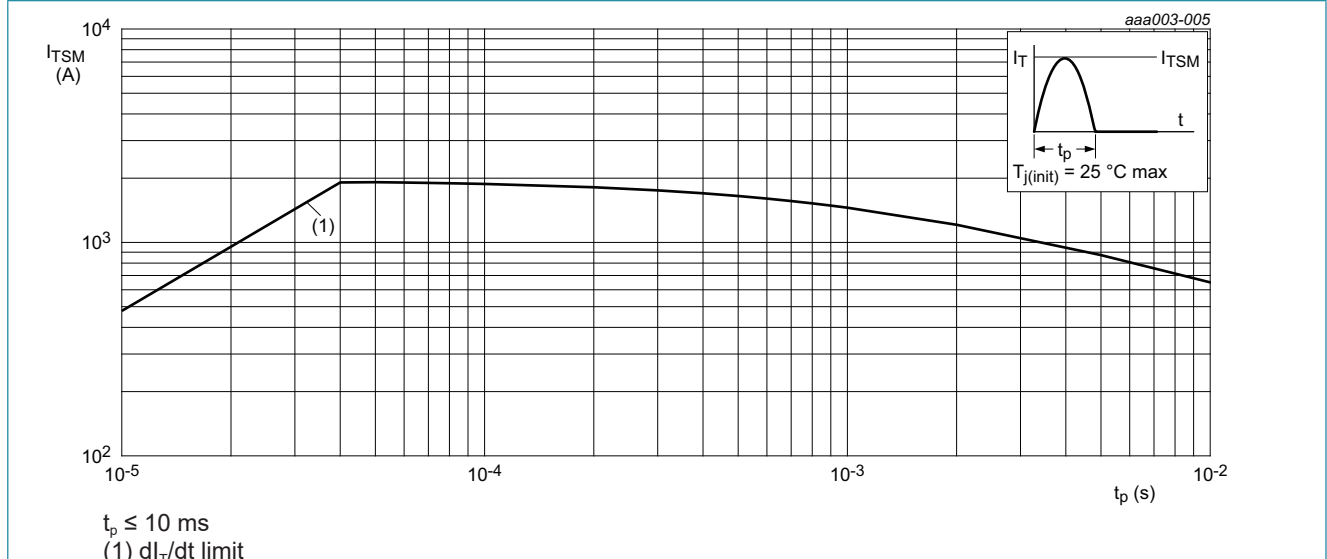


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

## 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter   | Conditions        | Min | Typ | Max  | Unit |
|----------------|---|-------------------|-----|-----|------|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | full cycle; Fig 6 | -   | -   | 0.25 | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient       | in free air       | -   | 50  | -    | K/W  |

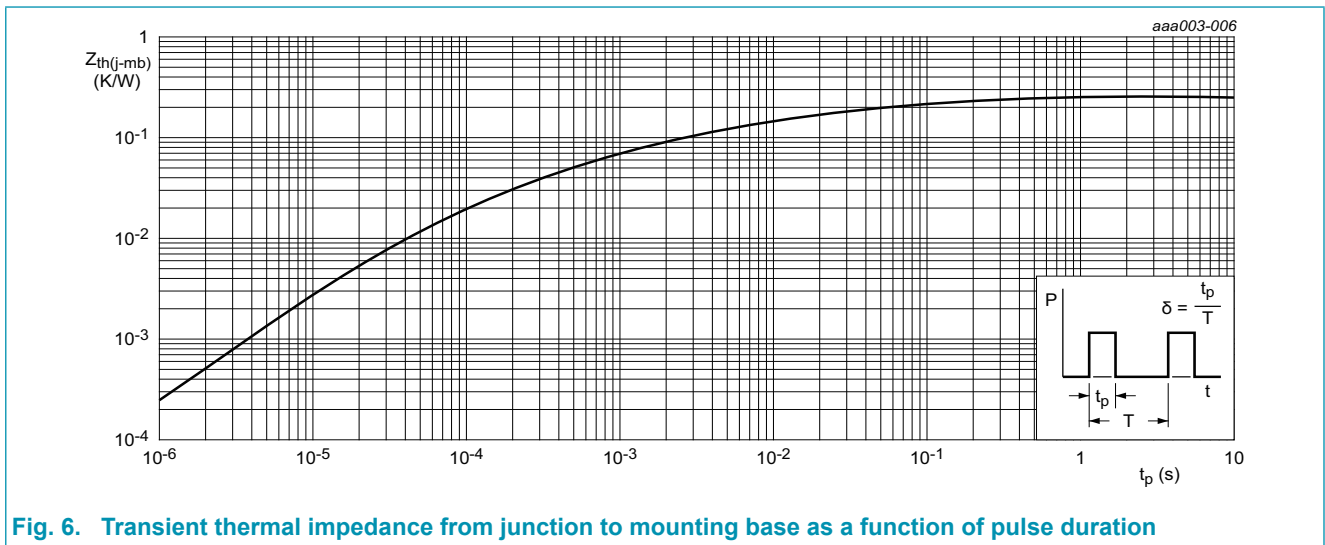


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

Table 7. Characteristics

| Symbol                         | Parameter                         | Conditions  | Min  | Typ | Max | Unit       |
|--------------------------------|-----------------------------------|---|------|-----|-----|------------|
| <b>Static characteristics</b>  |                                   |   |      |     |     |            |
| $I_{GT}$                       | gate trigger current              | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_j = 25\text{ }^\circ\text{C};$<br><a href="#">Fig. 7; Fig. 8</a>  | -    | -   | 50  | mA         |
| $I_L$                          | latching current                  | $V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_j = 25\text{ }^\circ\text{C};$<br><a href="#">Fig. 9</a>  | -    | -   | 300 | mA         |
| $I_H$                          | holding current                   | $V_D = 12\text{ V}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 10</a>  | -    | -   | 200 | mA         |
| $V_T$                          | on-state voltage                  | $I_T = 50\text{ A}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>  | -    | -   | 1.3 | V          |
|                                |                                   | $I_T = 90\text{ A}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>  | -    | -   | 1.5 | V          |
| $V_{GT}$                       | gate trigger voltage              | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_j = 25\text{ }^\circ\text{C};$<br><a href="#">Fig. 12</a>   | -    | 0.7 | 1   | V          |
|                                |                                   | $V_D = 800\text{ V}; I_T = 0.1\text{ A}; T_j = 125\text{ }^\circ\text{C};$<br><a href="#">Fig. 12</a>   | 0.25 | 0.4 | -   | V          |
| $I_D$                          | off-state current                 | $V_D = 1200\text{ V}; T_j = 125\text{ }^\circ\text{C}$  | -    | -   | 3   | mA         |
| $I_R$                          | reverse current                   | $V_D = 1200\text{ V}; T_j = 125\text{ }^\circ\text{C}$  | -    | -   | 3   | mA         |
| <b>Dynamic characteristics</b> |                                   |   |      |     |     |            |
| $dV_D/dt$                      | rate of rise of off-state voltage | $V_{DM} = 804\text{ V}; T_j = 125\text{ }^\circ\text{C}; R_{GK} = 100\text{ }\Omega;$<br>( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform   | 1500 | -   | -   | V/ $\mu$ s |
|                                |                                   | $V_{DM} = 804\text{ V}; T_j = 150\text{ }^\circ\text{C}; R_{GK} = 100\text{ }\Omega;$<br>( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform   | 1000 | -   | -   | V/ $\mu$ s |
| $t_{gt}$                       | gate-controlled turn-on time      | $I_{TM} = 40\text{ A}; V_D = 800\text{ V}; I_G = 0.1\text{ A}; dI_G/dt = 5\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}$  | -    | 2   | -   | $\mu$ s    |
| $t_q$                          | commutated turn-off time          | $V_{DM} = 804\text{ V}; T_j = 125\text{ }^\circ\text{C}; I_{TM} = 20\text{ A}; V_R = 25\text{ V}; (dI_T/dt)_M = 30\text{ A}/\mu\text{s}; dV_D/dt = 50\text{ V}/\mu\text{s}; R_{GK(ext)} = 100\text{ k}\Omega; (V_{DM} = 67\%$ of $V_{DRM})$ | -    | 150 | -   | $\mu$ s    |

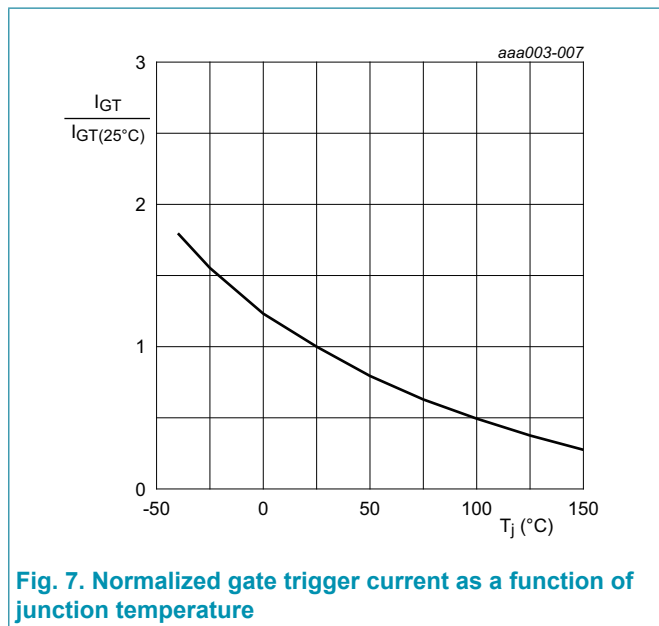


Fig. 7. Normalized gate trigger current as a function of junction temperature

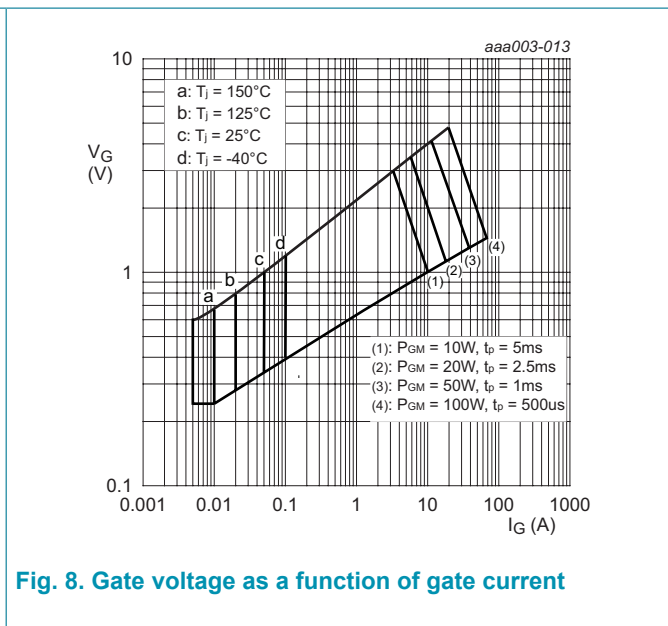


Fig. 8. Gate voltage as a function of gate current

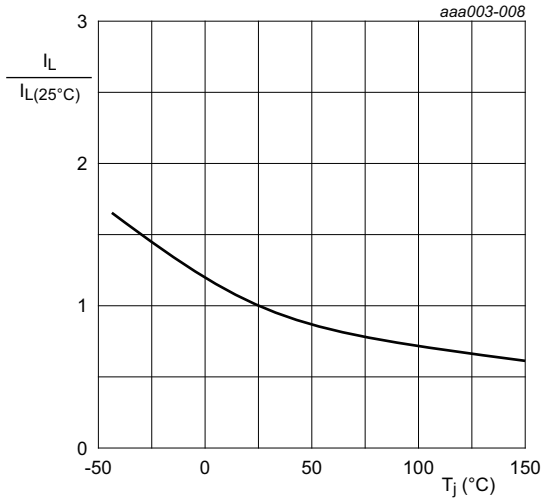


Fig. 9. Normalized latching current as a function of junction temperature

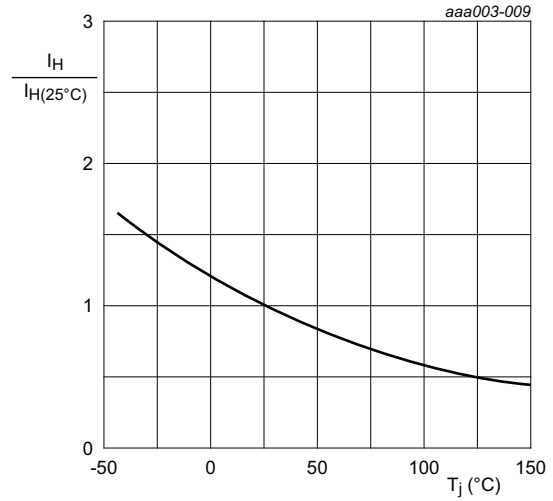
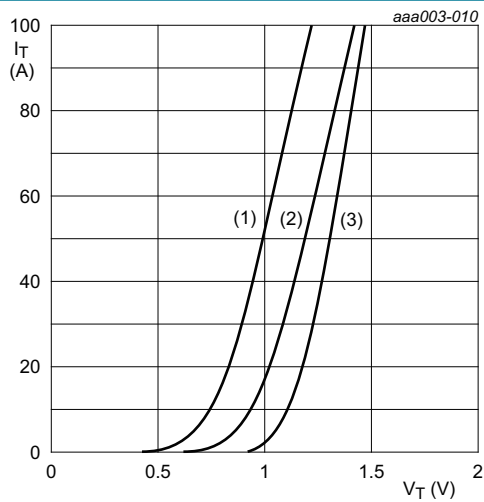


Fig. 10. Normalized holding current as a function of junction temperature



$V_o = 0.975 \text{ V}; R_s = 0.0044 \ \Omega$   
 (1)  $T_j = 150 \text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_j = 150 \text{ }^\circ\text{C}$ ; maximum values  
 (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; maximum values

Fig. 11. On-state current as a function of on-state voltage

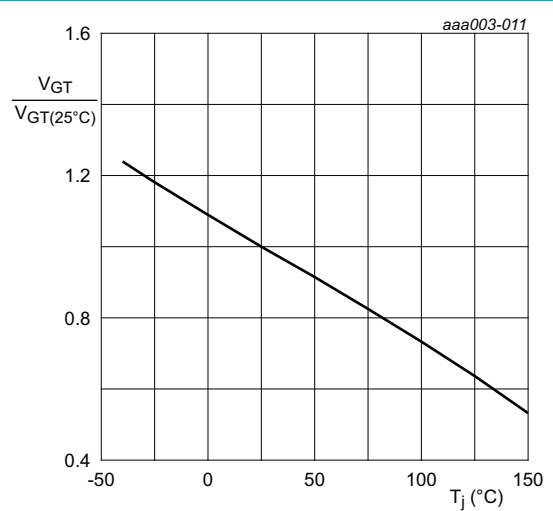
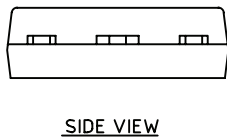
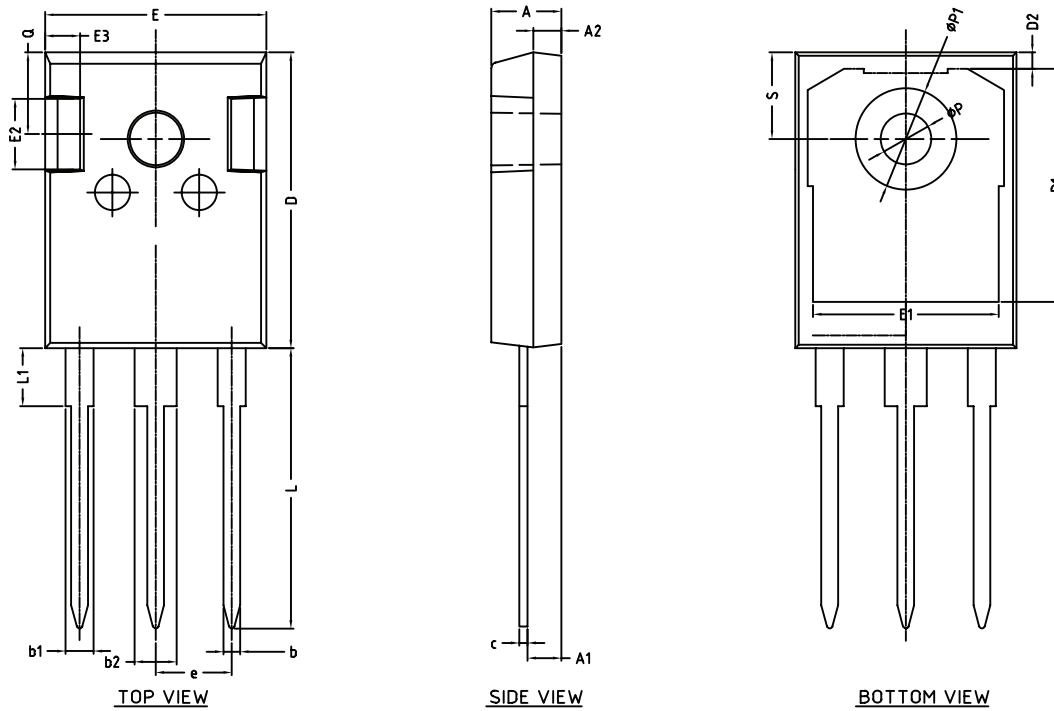


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

### 11. Package outline

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3-lead TO-247

SOT429N



| UNIT | A   | A1   | A2   | b    | b1   | b2   | c    | D    | D1    | D2    | E    | E1    | E2    | E3   | e    | L     | L1    | P    | P1   | Q    | S    |      |
|------|-----|------|------|------|------|------|------|------|-------|-------|------|-------|-------|------|------|-------|-------|------|------|------|------|------|
| mm   | MAX | 5.20 | 2.60 | 2.10 | 1.40 | 2.20 | 3.20 | 0.70 | 21.10 | 16.85 | 1.35 | 15.90 | 13.50 | 5.20 | 2.60 | 5.45  | 20.10 | 4.75 | 3.70 | 7.40 | 6.00 | 6.25 |
|      | MIN | 4.70 | 2.20 | 1.90 | 1.00 | 1.80 | 2.80 | 0.50 | 20.90 | 16.25 | 1.05 | 15.70 | 13.10 | 4.80 | 2.40 | 19.80 | -     | 3.50 | -    | 5.60 | 6.05 |      |

| OUTLINE VERSION | REFERENCES |        |      |  | PROJECTION | ISSUE DATE |
|-----------------|------------|--------|------|--|------------|------------|
|                 | IEC        | JEDEC  | EIAJ |  |            |            |
| SOT429N         |            | TO-247 |      |  |            |            |



## 12. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.ween-semi.com>.

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For sales office addresses, please send an email to: [salesaddresses@ween-semi.com](mailto:salesaddresses@ween-semi.com)  
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